

# Aluminum Nitride Cross-Sectional Lamé Mode Resonators with 260 MHz Lithographic Tuning Capability and High $k_t^2 > 4\%$

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**Abstract**—We experimentally demonstrate Aluminum Nitride (AlN) cross-sectional Lamé mode resonators (CLMRs) operating in the microwave frequency range and showing high  $Q \cdot k_t^2$  products (FoM) in excess of 85. Such feature enables low motional resistance ( $R_m$ ) values (37  $\Omega$ ) in CLMRs characterized by low static capacitance ( $C_0$ ) approaching 66 fF. In addition, the ability of CLMRs to simultaneously achieve high  $k_t^2 (> 4\%)$  and a lithographic frequency tunability ( $> 260$  MHz around 900 MHz) is experimentally demonstrated, for the first time, in this work. Such important feature renders CLMRs promising candidates to replace off-chip Surface Acoustic Wave (SAW) devices in lithographically defined filters for next-generation wireless communication platforms.

**Keywords**—Acoustic resonators, filters, electromechanical coupling coefficient, Aluminum Nitride.

## I. INTRODUCTION

The steadily growing need of service bands in wireless communication platforms has increased the demand of miniaturized and high-performance low-power radio-frequency (RF) filters. Aluminum Nitride (AlN) resonators are promising candidates to replace off-chip Surface Acoustic Wave (SAW) devices in RF front-ends. In particular, thanks to their high-performance and small form-factor, filters based on AlN film-bulk-acoustic resonators (FBARs) have already replaced many SAW-based filters in commercial handsets [1]. However, as the resonance frequency of FBARs is set by their thickness, multi-frequency FBAR-based filters can be built on the same chip only through more elaborate fabrication processes. AlN contour-mode resonators (CMRs) appeared as promising candidates as AlN CMRs possess the ability of frequency tuning by lithography. However, the electromechanical-coupling coefficient ( $k_t^2$ ) of AlN CMRs is limited by the relatively weak piezoelectric coupling of the contour-extensional mode in AlN [2]. Only recently, AlN cross-sectional Lamé mode resonators have been demonstrated [3], [4]. Such devices can achieve similar  $k_t^2$  than FBARs, thus enabling comparable fractional-bandwidth (BW) than FBAR-based filters. However, as experimentally demonstrated in this work, the resonance frequency ( $f_r$ ) of CLMRs depends on the pitch of the metallic interdigitated transducers (IDTs) used to actuate and sense the mechanical vibration in AlN plates. Consequently, CLMR-based filters

operating at different center-frequencies can be monolithically integrated on the same chip without adding fabrication complexity and, consequently, rise the manufacturing cost. In this work, the electromechanical performance of CLMRs is investigated. In particular, the variation of electromechanical-coupling coefficient ( $k_t^2$ ), resonance frequency ( $f_r$ ) and resistance at resonance frequency ( $R_{fr}$ ) (i.e. the sum of series resistance  $R_s$  and motional resistance  $R_m$ ), with respect to the pitch of the IDTs ( $W$ ) are investigated in CLMRs made out of 4  $\mu\text{m}$  of AlN. Our experiments demonstrate that CLMRs can achieve high- $k_t^2 (> 4\%)$  in a large lithographically defined bandwidth (260 MHz around 900 MHz).

Furthermore, we demonstrate a high  $Q \cdot k_t^2$  product (figure of merit, FoM) in excess of 85 in a CLMR (Figure 1) characterized by low static-capacitance ( $C_0 \sim 66$  fF). Such high value of FoM is to the authors' knowledge the highest ever reported in AlN resonators using IDTs.

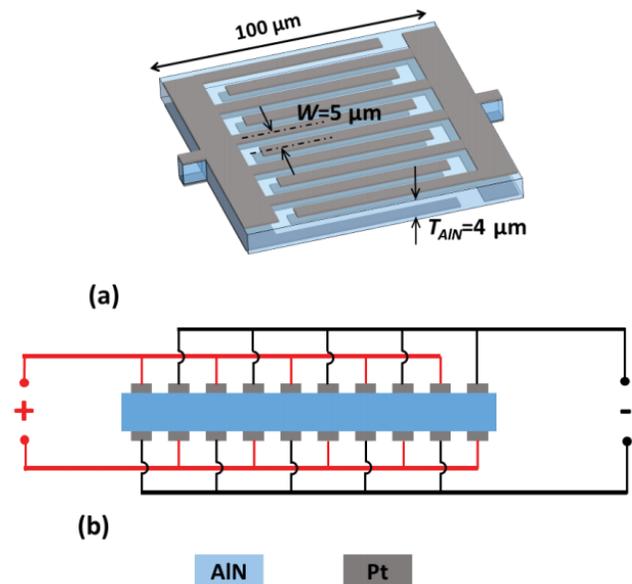


Figure 1: (a) 3D schematic representation, (b) cross-sectional view of CLMRs.

## II. EXPERIMENTAL RESULTS

The devices were built using a 4-mask fabrication process, as shown in Figure 2. A 100 nm thick platinum (Pt) layer was firstly deposited and patterned by liftoff on a high resistivity silicon (Si) wafer to define the bottom IDT. A 4  $\mu\text{m}$  thick AlN was then sputter-deposited and wet etched to form the vias. After that, a 100 nm Pt was again deposited and patterned for the top electrode. The shape of the resonant plate was defined by dry etch with a hard mask made of 2  $\mu\text{m}$  SiO<sub>2</sub>. Finally, the devices were structurally released by XeF<sub>2</sub> isotropic etching of Si. Quarter-wave ( $\lambda/4$ ) transformers were integrated between the edge of the active region and each adjacent anchor for all the devices in order to minimize the anchor dissipation [5]. The length of the CLMRs was designed to be 100  $\mu\text{m}$ , and the overall width was set by the pitch,  $W$ , and the number of finger (Figure 3).

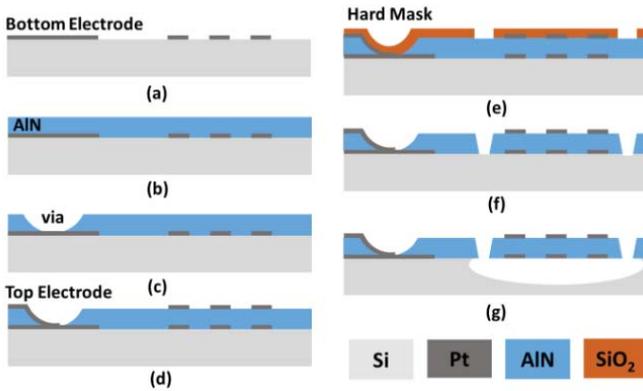


Figure 2: Microfabrication process: (a) sputter deposition and liftoff of Pt bottom electrodes; (b) deposition of 4  $\mu\text{m}$  AlN; (c) wet etch of AlN for vias; (d) sputter deposition and liftoff of Pt top electrodes; (e) deposition and etch of 2  $\mu\text{m}$  SiO<sub>2</sub> as hard-mask; (f) dry etch of AlN; (g) XeF<sub>2</sub> dry release.

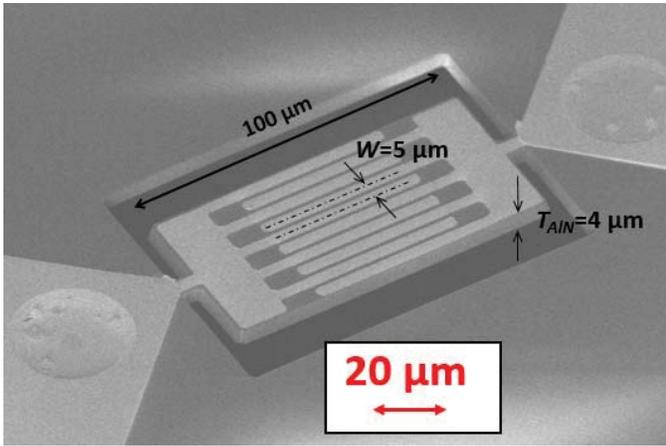


Figure 3. Scanning electron microscope (SEM) image of a 10-finger CLMR fabricated in this work.

The experiments were carried out based on 18 fabricated resonators with 5 different pitches ( $W = 3, 4, 5, 6,$  and  $7 \mu\text{m}$ ). The dependences of  $k_t^2$  and  $f_r$  on the pitch size ( $W$ ) of the IDTs were investigated. The measured average  $k_t^2$  values, and

simulated  $k_t^2$  values (by 3D finite element analysis using CoventorWare) for each pitch size are reported in Figure 4. Evidently, the measured average  $k_t^2$  reached its peak when the pitch size was selected to be around 5 to 6  $\mu\text{m}$ . And an almost identical trend can be found in the simulation results. Such optimized pitch enables the excitation of a non-degenerate cross-sectional Lamé mode in a 4  $\mu\text{m}$  thick AlN plate sandwiched between two 100 nm thick platinum IDTs.

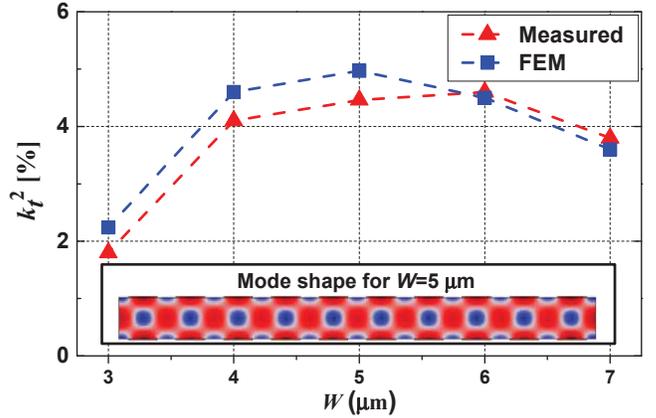


Figure 4: (a) Measured (in red) and 3D simulated (in blue)  $k_t^2$  as a function of the pitch of the IDTs used to actuate and sense the mechanical motion in CLMRs. All tested devices have a 60% metal coverage independently on  $W$ . The FEM simulated mode-shape relative to the total displacement of the fabricated CLMRs is also reported; as evident, a high  $k_t^2$  value in excess of 4% can be achieved by selecting  $W$  to be included between 4 and 6.5  $\mu\text{m}$ .

The measured resonance frequencies and  $k_t^2$  values for each pitch,  $W$ , are reported in Figure 5, showing that CLMRs can achieve high- $k_t^2$  ( $> 4\%$ ) in a large lithographically defined bandwidth ( $> 260$  MHz around 900 MHz). Such lithographic tuning capability is sufficient to form filters for next-generation mobile platforms adopting carrier-aggregation and permits to build both transmit and receive filters on the same chip without complicating the fabrication process [6].

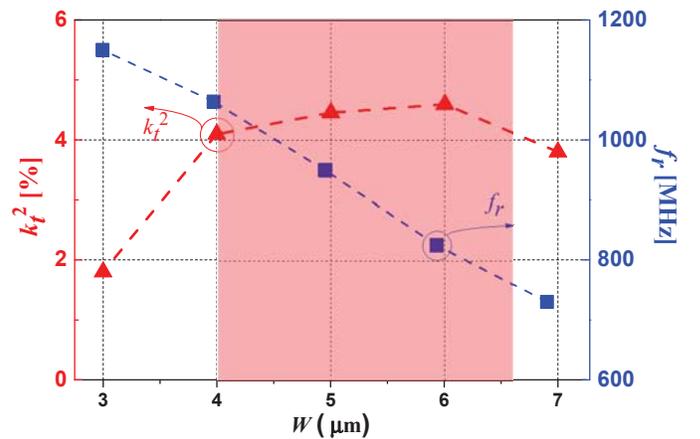


Figure 5: (a) Measured  $k_t^2$  (in red) and resonance frequencies (in blue) as a function of pitch,  $W$ . All tested devices have a 60% metal coverage independently on  $W$ . The shadowed area highlights the pitch sizes and corresponding frequency range (from  $\sim 770$  MHz to  $\sim 1.03$  GHz) where CLMRs can be lithographically tuned while preserving high  $k_t^2 > 4\%$ .

The highest loaded quality factor,  $Q_{load}$ , measured for each pitch size and the corresponding total resistance at resonance frequency,  $R_{fr}$  ( $R_s + R_m$ ), extracted from modified Butterworth-Van Dyke (MBVD) model fitting are reported in Figure 6, showing a low impedance of CLMRs for potential direct integration with 50  $\Omega$  electronics.

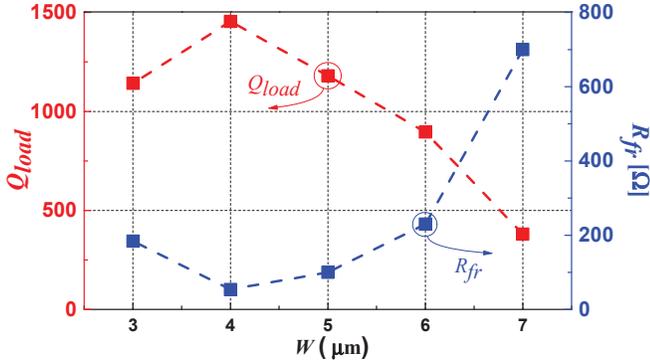


Figure 6: Measured  $R_{fr}$  (in blue) and  $Q_{load}$  (in red) as a function of pitch when metal coverage is set to 60% of the pitch. Lowest  $R_{fr}$  and high  $Q_{load}$  present for pitches of 4  $\mu\text{m}$ .

Furthermore, the measured, simulated and fitted (through MBVD fitting) admittance curves of the best fabricated CLMR are shown in Figure 7. A  $Q_{load}$  in air of 1635 and a  $k_t^2$  of 4.3% were recorded, thus resulting into a FoM close to 85. Such value is, to the best of our knowledge, the highest ever reported in AlN resonators using IDTs to actuate and sense the mechanical vibration in the AlN plate. The measured response was de-embedded from parasitic capacitance and series resistance due to the probing-pads. As evident both the measured and the simulated responses are affected by a spurious-mode (at 950 MHz in measurement) close to the device parallel resonance frequency. This mode, which is a higher-order Lamb-wave mode, can be suppressed in the future through the strategic optimization of the geometry of the IDTs.

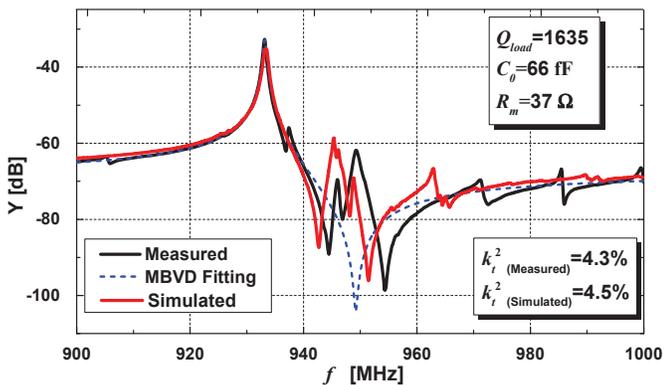


Figure 7: Measured (in black), fitted (in blue) and simulated (in red) responses of the best CLMR recorded in this work. An 80 MHz resonance frequency shift observed between measurement and simulation results is believed to be caused by inaccurate definition of material parameters and device dimensions.

### III. CONCLUSION

In this paper, aluminum nitride (AlN) cross-sectional Lamé mode resonators (CLMRs) operating in the microwave frequency range were designed, fabricated and characterized, showing a record high  $Q \cdot kt_2$  products in excess of 85. In addition, for the first time, the ability of CLMRs to simultaneously achieve high electromechanical-coupling ( $k_t^2 > 4\%$ ) and a lithographic tuning capability of frequency ( $> 260$  MHz around 900 MHz) was experimentally demonstrated. Such achievements of CLMRs set a stepping stone towards the development of next generation monolithically integrated mobile platforms featuring wide spectrum coverage and low loss.

### ACKNOWLEDGMENT

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### REFERENCES

- [1] R. C. Ruby, P. Bradley, Y. Oshmyansky, A. Chien, and J. D. Larson III, "Thin film bulk wave acoustic resonators (FBAR) for wireless applications," in *Ultrasonics Symposium, 2001 IEEE*, 2001, vol. 1, pp. 813–821.
- [2] Y. Hui, Z. Qian, and M. Rinaldi, "A 2.8 GHz combined mode of vibration aluminum nitride MEMS resonator with high figure of merit exceeding 45," in *European Frequency and Time Forum & International Frequency Control Symposium (EFTF/IFC), 2013 Joint*, 2013, pp. 930–932.
- [3] C. Cassella, Y. Hui, Z. Qian, G. Hummel, and M. Rinaldi, "Aluminum Nitride Cross-Sectional Lamé Mode Resonators," *J. Microelectromechanical Syst.*, pp. 1–11, 2016.
- [4] C. Cassella and G. Piazza, "AlN Two-Dimensional-Mode Resonators for Ultra-High Frequency Applications," *IEEE Electron Device Letter*, vol. 36, no. 11, pp. 1192–1194, Nov. 2015.
- [5] C. Cassella, N. Singh, G. Piazza, and B. W. Soon, "Quality Factor Dependence on the Inactive Regions in AlN Contour-Mode Resonators," *J. Microelectromechanical Syst.*, vol. 10.1109, no. JMEMS.2015.2423663.
- [6] M. Rinaldi, C. Zuo, J. Van der Spiegel, and G. Piazza, "Reconfigurable CMOS Oscillator Based on Multifrequency AlN Contour-Mode MEMS Resonators," *IEEE Trans. Electron Devices*, vol. 58, no. 5, pp. 1281–1286, May 2011.